



March 4, 2008

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 09/821,546 03/30/2001

J. Y. LEE

"A STRUCTURE AND MANUFACTURING
METHOD OF CHIP SCALE PACKAGE"

Grp. Art Unit: 2811

VU, HUNG K.

AMENDMENT AND RESPONSE TO NON-FINAL OFFICE ACTION

Dear Sir:

In response to the Non-Final Office Action mailed Oct. 5, 2007, please amend the above-identified application for patent and consider the remarks as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on Mar. 5, 2008.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date 3/5/08

A handwritten signature in black ink, appearing to be "SBA", written over a horizontal line.